



Keynote speaker:

Prof. Dr.-Ing. habil. Dr. H. C. Mult. Klaus-Jürgen Wolter

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Presentation:

"Automotive Electronics Packaging Trends"

Prof. Klaus Wolter's research interests have embraced many aspects of microelectronics packaging, including substrate technologies, assembly technologies, photonic packaging, MEMS, joining technologies, reliability of electronic packages, and non-destructive test methods.

He is well known as the co-editor and co-author of six textbooks, co-editor of three book series with a total of 39 books, author and co-author of more than 200 papers.

He is a senior member of IEEE-CPMT.

Prof. Wolter was the Director of the Electronic Packaging Lab at TU Dresden from 2003 to 2014. From March 2015 to March 2017, he was a visiting professor at the 3D Systems Packaging Research Center of Georgia Tech Atlanta where he researched on system-integration for advanced automotive electronics. Currently he is a senior professor at TU Dresden.